ABSTRACT

INTEGRATED CIRCUIT LEADFRAME WITH GROUND PLANE

A leadframe for a semiconductor package includes signal and ground leads, a ground plane, and a frame paddle. Supports connect the signal and ground leads, ground plane, and frame paddle in at least two different layers. At least one force release and stress relief structure is incorporated into the leadframe to free the ground plane substantially from distortion and warpage resulting from residual mechanical stresses therein.

(Fig. 1)